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FOR LCD MODULE

MODULE NO: AFK640480A3-5.7N6NTH REVISION NO: V04

	SIGNATURE	DATE
PREPARED BY (RD ENGINEER)		
CHECKED BY		
APPROVED BY		

Customer's Approval:

Records of Revision

DATE	REF.PAGE PARAGRAPH DRAWING No.	REVISED No.	SUMMARY	REMARK
2015-2-9		V01	First Issue	
2015-10-28	Page5	V02	Update the drawing	
2015-11-20	Page10	V03	Add the minimum value of luminance	
2015-11-25	Page5	V04	Update the drawing	

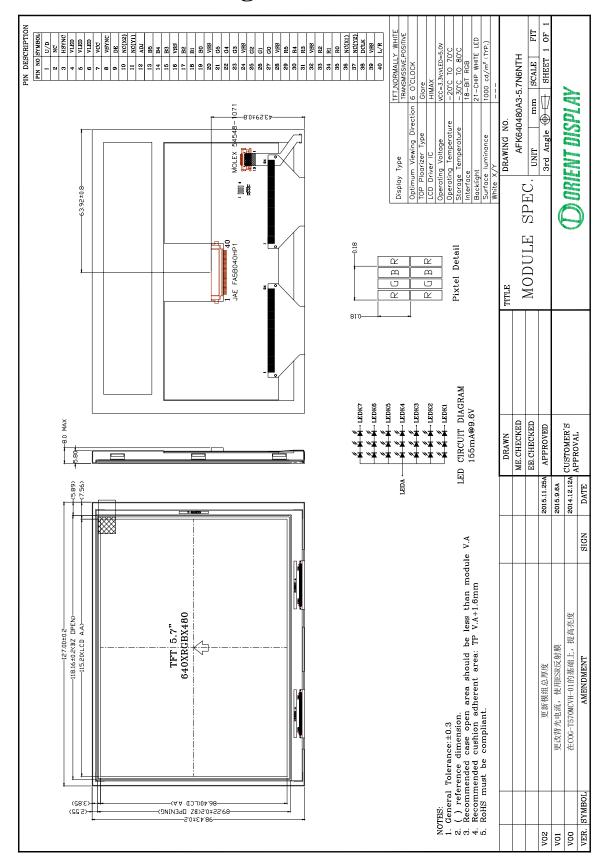
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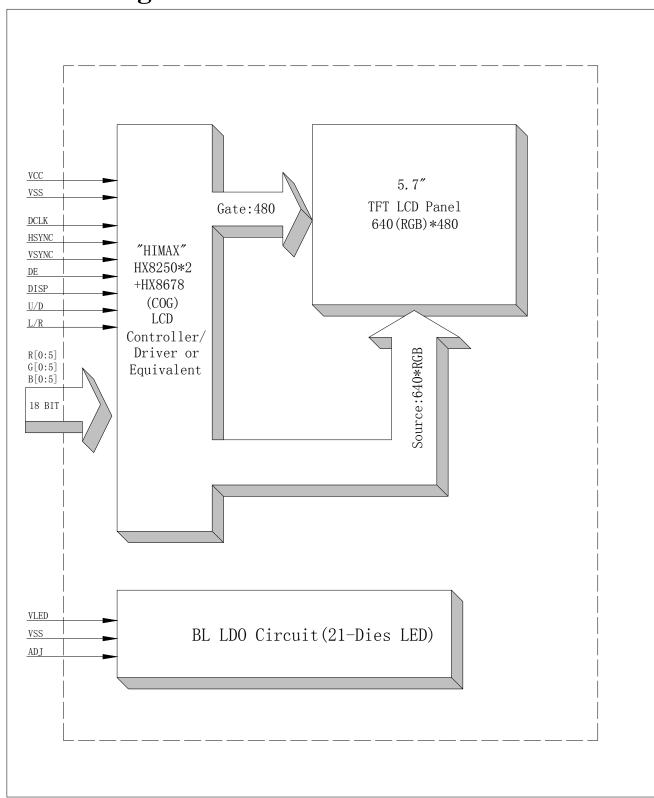
1. General Specification

Item	Contents	Unit
LCD TYPE	TFT/TRANSMISSIVE	
MODULE SIZE (W*H*T)	127.0*98.43*7.0	MM
ACTIVE SIZE (W*H)	115.2*86.4	MM
PIXEL PITCH (W*H)	0.18*0.18	MM
NUMBER OF DOTS	640*480	
DIVER IC	HX8250*2+HX8678	
INTERFACE TYPE	18-BIT RGB	
TOP POLARIZER TYPE	GLARE	
RECOMMEND VIEWING DIRECTION	6	O'CLOCK
GRAY SCALE INVERSION DIRECTION	12	O'CLOCK
COLORS	262K	
BACKLIGHT TYPE	21-DIES WHITE LED	
TOUCH PANEL TYPE	Without	

2. Mechanical Drawing



3. Block Diagram



4. Interface Pin Function

Pin No.	Symbol	Description
1	U/D	Up/down scan setting. When U/D=H, reverse scan. When U/D=L, normal scan.
2	NC	No connection.
3	HSYNC	Horizontal sync input in digital RGB and CCIR601 mode. (Short to GND if not used)
4~6	VLED	Power supply for BLU LDO circuit.
7	VCC	Power supply.
8	VSYNC	Vertical sync input in digital RGB and CCIR601 mode. (Short to GND if not used)
9	DE	Input data enable control. When DE mode, active High to enable data input. Default pull low.
10	NC(X2)	No connection.(Touch panel control PIN: X2)
11	NC(Y1)	No connection.(Touch panel control PIN: Y1)
12	ADJ	Chip Enable (Active High).
13~15	B5~B3	Blue data input.
16	VSS	Power ground.
17~19	B2~B0	Blue data input.
20	VSS	Power ground.
21~23	G5~G3	Green data input.
24	VSS	Power ground.
25~27	G2~G0	Green data input.
28	VSS	Power ground.
29~31	R5~R3	Red data input.
32	VSS	Power ground.
33~35	R2~R0	Red data input.
36	NC(X1)	No connection.(Touch panel control PIN: X1)
37	NC(Y2)	No connection.(Touch panel control PIN: Y2)
38	DCLK	Clock signal. Latching data at the rising edge.
39	VSS	Power ground.
40	L/R	The shift direction of device internal shift register is controlled by this pin as shown below: L/R=H: STH->SO1->• • •->SO960->STHO L/R=L: STH->SO960->• • •->SO1->STHO

5. Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Supply voltage for analog	VCC	-0.3	7.0	V
Supply voltage for logic	VCC	-0.3	7.0	V
Supply voltage for BLU LDO circuit	VLED	-0.3	7.0	V
Supply current (One LED)	$I_{ m LED}$		65	mA
Operating temperature	T_{OP}	-20	+70	°C
Storage temperature	T_{ST}	-30	+80	°C

Note: The absolute maximum rating values of this product are not allowed to be exceeded at any times. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.

6. Electrical Characteristics

6.1 Input Power

Item	Symbol	Min	Тур.	Max	Unit	Applicable terminal
Supply Voltage for Analog	VCC	2.7	3.3	3.6	V	
Supply Voltage for Logic	VCC	2.7	3.3	3.6	V	
Input Voltage	$V_{ m IL}$	GND	ı	0.3VCC	V	
input voitage	$V_{ m IH}$	0.7 VCC	1	VCC	V	
Input leakage Current	I_{LKG}	-1		1	μΑ	

6.2 Backlight Driving Conditions

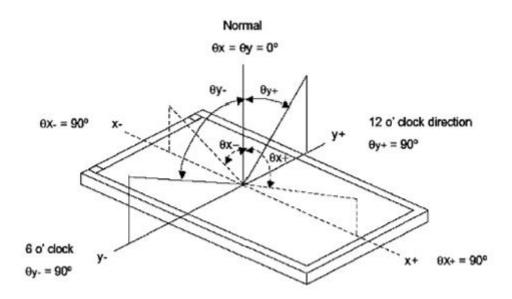
Itom	Cymbol	Value			Unit	Remark
Item	Symbol	Min.	Тур.	Max.	UIIIt	Kemark
Voltage for BLU LDO circuit	VLED	2.7	5.0	5.5	V	
Current for BLU LDO circuit	I		333		mA	
Power Consumption	Р		1.665		W	
LED Life Time		30,000			Hr	Note

Note: Brightness to be decreased to 50% of the initial value at ambient temperature TA=25 $^{\circ}$ C

7. Optical Characteristics

IGUEN	Л	CYMPOI	CONDITIONS	SPEC	IFICAT	ΓΙΟΝS	TINITE	NOTE
ITEN	/1	SYMBOL	CONDITIONS	MIN	TYP.	MAX	UNIT	NOTE
Lumina	nce	L		900	1000		Cd/m ²	
Contrast I	Ratio	CR	θ=0°		250			
Dagnanga	Timo	Ton	25℃		50		me	
Response Time		Toff	23 0		30		ms	
	Red	XR						
	Keu	YR						
	Green	XG	Viewing normal angle					
CIE Color	Green	YG						
Coordinate	Blue	Хв						
	Diue	YB						
	White	Xw			0.2945			
	winte	Yw			0.3255			
	Hor.	$ heta_{\scriptscriptstyle X+}$			45			
Viewing Angle	1101.	$ heta_{\scriptscriptstyle X-}$	CR≥10		45		Dagge	
	Ver.	$ heta_{\scriptscriptstyle{Y+}}$	CK > 10		35		Degree	
	V C1.	$ heta_{\scriptscriptstyle Y-}$			15			
Uniformity	Un			80			%	

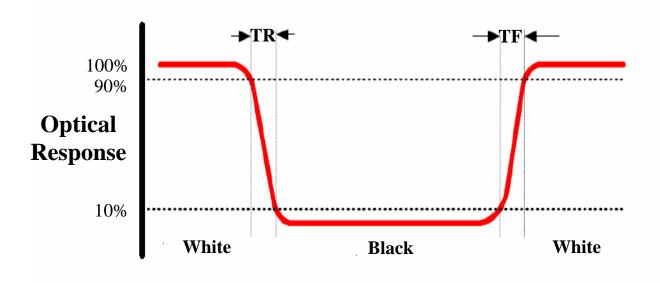
Note 1: Definition of Viewing Angle θx and θy :



Note 2: Definition of contrast ratio CR:

$$CR = \frac{Luminance of white state}{Luminance of black state}$$

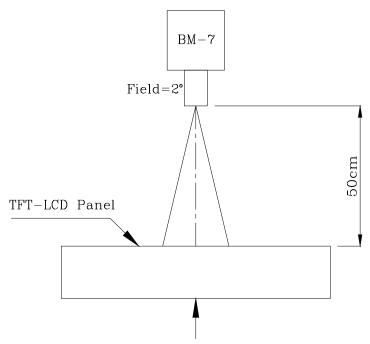
Note 3: Definition of Response Time(Tr,Tf)



Note 4: Definition of Luminance

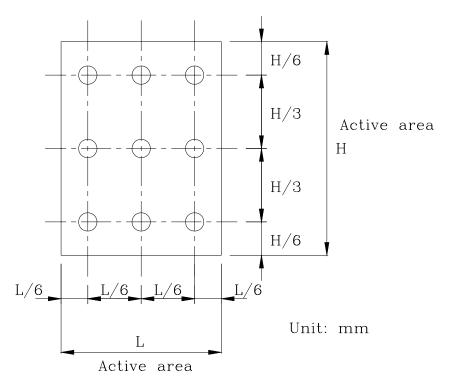
①The Brightness Test Equipment Setup

Field=2° (As measuring "black" image, field=2° is the best testing condition)



The center of the screen

②The Brightness Test Point Setup



8. Timing Characteristics

8.1 AC Electrical Characteristics

PARAMETER	Symbol		Spec.		Unit
PARAMETER	Syllibol	Min.	Тур.	Max.	Oilit
HS setup time	T _{hst}	10	-	-	ns
HS hold time	T _{hhd}	10	-	-	ns
VS setup time	T _{vst}	10	-	- (ns
VS hold time	T_{vhd}	10	-	O. 5//	ns
Data setup time	T _{dsu}	10	-	V) () C	ns
Data hold time	T _{dhd}	10	-		ns
DEN setup time	T _{esu}	10	- (\\-	ns
VS falling to HS falling time	т	-4	9	+4	4
on odd field @ RGB mode	T _{HV_O}	-4	(0%)	74	T_{CPH}
VS falling to HS falling time on	Т	0.4	0.5	0.6	T _H
even field @ RGB mode	T _{HV_E}	0.4	30.5	0.0	Ŧ
Source output settling time	T _{ST}	(F)	12	20	μs
Source output loading R	$R_{\scriptscriptstyle{SL}}$	5-1	2		K ohm
Source output loading C	C _{SL}		60		рF
POL output delay time	T_{DP}	V- /		40	ns

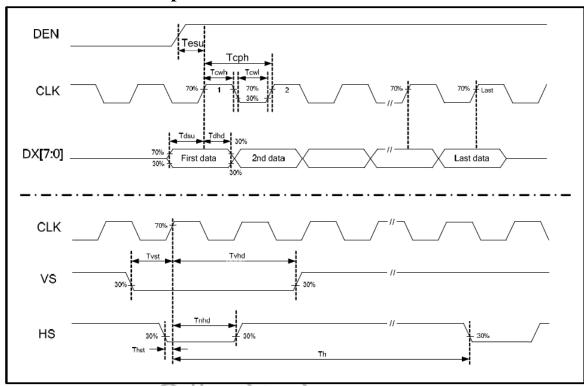
8.2 Digital Parallel RGB interface

PARAMETER	Symbol		Spec.		Unit
FARAMETER	Syllibol	Min.	Тур.	Max.	Ollit
CLK frequency	F _{CPH}	•	25.175	-	MHz
CLK period	T _{CPH}	-	39.7	-	ns
CLK pulse duty	T_{CWH}	40	50	60	%
HS period	T _H	-	800	-	T _{CPH}
HS pulse width	T _{WH}	5	30	-	T _{CPH}
HS-first horizontal data time	T _{HS}	112	144	175	T _{CPH}
DEN pulse width	T _{EP}	-	640	-	Торн
VS pulse width	Twv	1	3	5 (T _H
VS-DEN time	T _{STV}	-	35	~ ` (U/T _H
VS period	T _V	-	525	ES-//	T _H

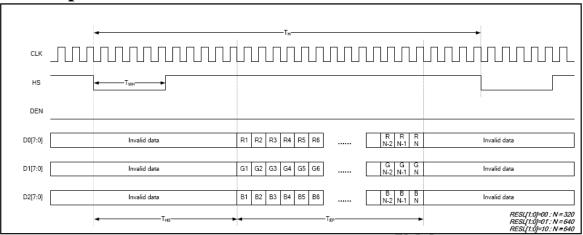
Note: When SYNC mode is used, 1st data start from 144th CLK after HS falling (when STHD[5:0]=00000)

PARAMETER	Symbol		Unit		
TAKAMETEK	Syllibol	Min.	Тур.	Max.	Offic
OEV pulse width	T _{OEV}	- (100	7	T _{CPH}
CKV pulse width	T _{CKV}	100	96		T _{CPH}
HS-CKV time	T ₁	(3/)	52	$\langle O \rangle$	T _{CPH}
HS-OEV time	T ₂		8	7//	T_{CPH}
HS-POL time	T ₃ <	\bigcirc	72)) Y	T_{CPH}
STV setup time	T _{SUV}	\) - (46	-	T_{CPH}
STV pulse width	T _{WSTV}	- \		-	T _H

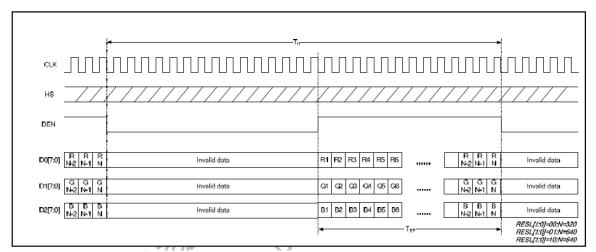
8.3 Clock and Data input waveforms



8.4 Data input format for RGB mode



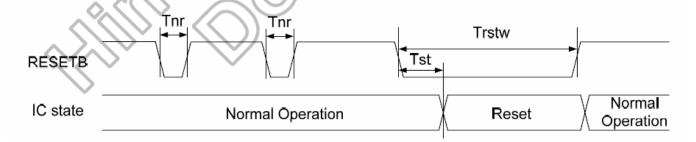
Parallel RGB SYNC Mode Horizontal Data Format



Parallel RGB DE Mode Horizontal Data Format

8.5 Hardware reset timing

PARAMETER	Symbol		Unit			
PARAMETER	Syllibol	Min.	Тур.	Max.	Oilit	
RESETB low pulse width	T _{rstw}	10	-	-	μs	
Negative noise pulse width	T _{nr}		-	2	μs	
Reset start time	T _{st}	2	-		μs	



9. Standard Specification for Reliability

9.1 Standard Specification for Reliability of LCD Module

No.	Item	Description
01	High temperature operation	The sample should be allowed to stand at 70°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
02	Low temperature operation	The sample should be allowed to stand at -20° C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
03	High temperature storage	The sample should be allowed to stand at 80°C for 240 hours under no-load condition, and then returning it to normal temperature condition, and allowing it stand for 2 hours.
04	Low temperature storage	The sample should be allowed to stand at -30°C for 240 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.
05	Moisture storage	The sample should be allowed to stand at 60°C,90%RH MAX for 240 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles: -30°C for 30 minutes → normal temperature for 5 minutes → +80°C for 30 minutes → normal temperature for 5 minutes, as one cycle.
07	Packing vibration	Frequency range: 10Hz ~ 55Hz Amplitude of vibration: 1.5mm Sweep time: 12 min X,Y,Z 2 hours for each direction.
08	Packing drop test	According to ASTM-D-5327.
00	Electrical	Air: ± 4 KV 150pF/330 Ω 5 times
09	Static Discharge	Contact: $\pm 2KV \ 150pF/330\Omega \ 5$ time

^{*}Sample size for each test item is 3~5pcs

9.2 Testing Conditions and Inspection Criteria

For the final test, the testing sample must be stored at room temperature for 24 hours. After the tests listed in Table 9.2, standard specifications for reliability will be executed in order to ensure stability.

No.	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

9.3 MTBF

Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature (25±5°C), normal humidity (50±10% RH), and in area not exposed to direct sun light.

10. Specification of Quality Assurance

This standard of Quality Assurance confirms to the quality of LCD module products supplied by OD.

10.1 Quality Test

Before delivering, the supplier should conduct the following tests to confirm the quality of products.

- Electrical-Optical Characteristics: According to the individual specification to test the product.
- Appearance Characteristics: According to the individual specification to test the product.
- Reliability Characteristics: According to the definition of reliability on the specification for testing products.

10.2 Delivery Test

Before delivering, the supplier should conduct the delivery test.

- Test method: According to MIL-STD105E.General Inspection Level II take a single Time.
- The defects classify of AQL as following:

Major defect: AQL = 0.65 Minor defect: AQL = 2.5 Total defects: AQL = 2.5

10.3 Non-conforming Analysis & Deal With Manners

10.3.1 Non-conforming Analysis

- Purchaser should provide the data detail of non-conforming sample and the non-conforming.
- After receiving the data detail from purchaser, the analysis of non-conforming should be finished within two weeks.
- If the analysis can't be finished on time, supplier must notice purchaser 3 days in advance.

10.3.2 Disposition of non-conforming

- If any product defect be found during assembling, supplier must change the good for every defect after confirmation.
- Both supplier and customer should analyze the reason and discuss the disposition of non-conforming when the reason of nonconforming is not sure.

10.4 Agreement items

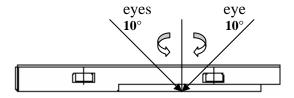
Both parties should negotiate together when the following problems happen.

- There is any problem of standard of quality assurance, and both sides should agree that it must be modified.
- There is any argument item which does not record in the standard of quality assurance.
- Any other special problem.

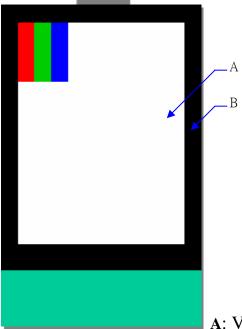
10.5 Standard of The Product Appearance Test

10.5.1 Manner of appearance test

- The test must be under 20W × 2 or 40W fluorescent light, and the distance of view must be at 30±5cm.
- When test the model of transmissive product must add the reflective plate.
- The test direction is base on around 10° of vertical line.
- Temperature: 25±5°C Humidity: 60±10%RH



• Definition of area:



A: Viewing area B: Outside viewing area

10.5.2 Basic principle

- When the standard can not be described, AQL will be applied.
- The sample of the lowest acceptable quality level must be negotiated by both supplier and customer when any dispute happened.
- New item must be added on time when it is necessary.

10.6 Inspection Specification

NO.	Item	Criterion				AQL
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Flicker 			0.65	
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	2.1 White and black or of Five spots.2.2 Densely spaced: No	•			2.5
	LCD and Touch Panel black		ely spaced	Size(mm) $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi \le 0.30$ $0.30 < \Phi$: No more than tw	Acceptable Q'ty Accept no dense 2 2 1 0 o spots within 3mm.	2.5
03	spots, white spots, contaminati on (non – display)	3.2 Line type: (As follows) W * Dens	Length(mm) L≦3.0 L≦2.5	Width(mm) $W \leq 0.02$ $0.02 < W \leq 0.05$ $0.03 < W \leq 0.08$ $0.08 < W$		2.5

NO.	Item	Criter	ion		AQL
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction	Size Φ(mm) $\Phi \le 0.20$ $0.20 < \Phi \le 0.50$ $0.50 < \Phi \le 1.00$ $1.00 < \Phi$ Total Q'ty	Acceptable Q'ty Accept no dense 3 2 0 3	2.5
05	Scratches	Follow NO.3 -2 Line Type.			
06	Chipped glass	x: Chip length y: Chip width z: Chip length y: Chip width z: Chip length t: Glass thickness a: L: Electrode pad length 6.1 General glass chip: 6.1.1 Chip on panel surface and crack to the surfac	between panels: $x: Chip leng$ $x \le 1/8a$ $x \ge 1/8a$ $x \ge 1/8a$	n chip	2.5

NO.	Item	Criterion	AQL
08	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
09	Backlight elements	 9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong. 	
10	Bezel	Bezel must comply with product specifications.	2.5
11	PCB、COB	 11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart. 	2.5 2.5 2.5 2.5 0.65
12	FPC	12.1 FPC terminal damage $\leq 1/2$ FPC terminal width and can not affect the function , we judge accept. 12.2 FPC alignment hole damage $\leq 1/2$ alignment area and can not affect the function , we judge accept.	2.5 2.5
13	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle. 13.2 No short circuits in components on PCB or FPC.	2.5 0.65

NO.	Item	Criterion	AQL
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 7.2 Protrusion over terminal: 7.2.1 Chip on electrode pad:	
		y: Chip width x: Chip length z: Chip thickness	
		$y \le 0.5 \text{mm} \qquad x \le 1/8 a \qquad 0 < z \le t$	
07	Glass crack	Non-conductive portion:	2.5
		y: Chip width x: Chip length z: Chip thickness	
		$y \le L \qquad \qquad x \le 1/8a \qquad \qquad 0 < z \le t$	
		 If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. If the product will be heat sealed by the customer, the alignment mark must mot be damaged. 7.2.3 Substrate protuberance and internal crack 	

NO.	Item		Criterion		AQL
14	Touch Panel Chipped glass	k: Seal width t: 'L: Electrode pad length 14.1 General glass class clas	gth	x: Chip length $x \le 1/8a$	2.5
		z: Chip thickness z≤t	y: Chip width ≤ 1/2 k and not over viewing area	x: Chip length $x \le 1/8a$	
		○ Unit: mm○ If there are 2 or n	nore chips, x is the total	length of each chip	

NO.	Item	Criterion	AQL
15	Touch Panel(Fish eye dent and bubble on film)	$\begin{array}{ c c c c }\hline SIZE(mm) & Acceptable Q'ty\\ \hline \Phi \leq 0.2 & Accept no dense\\ \hline 0.2 < D \leq 0.4 & 5\\ \hline 0.4 < D \leq 0.5 & 2\\ \hline 0.5 < D & 0\\ \hline \end{array}$	2.5
16	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion($\leq 2.5\%$), it is acceptable.	2.5
17	Touch Panel Linearity	Less than 2.5% is acceptable.	2.5
18	LCD Ripple	Touch the touch panel, can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g	2.5
19	General appearance	 19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet. 	0.65 0.65 0.65 0.65

11. Handling Precaution

11.1 Handling of LCM

- Avoid external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance, do not lick or swallow. When the liquid is attaching to your hand, skin, cloth, etc., wash it thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should wear protections whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface, be careful when peeling off this protective film since static electricity may be generated.

11.2 Storage

- Store it in an ambient temperature of 25±10°C, and in a relative humidity of 50±10% RH. Don't expose to sunlight or fluorescent light.
- Store it in a clean environment, free from dust, active gas, and solvent.
- Store it in anti-static electricity container.
- Store it without any physical load.

11.3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: no higher than 280±10°C and less than 3 sec during hand soldering.
- Rewiring: no more than 2 times.

12. Packing Method

----TBD